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PRODUCT CHANGE NOTIFICATION

PCN: PCN170701

Date: February 15, 2017

Subject: Qualification of Texas Instruments' DMOS6 as an Additional Wafer Fab Site, Cypress' Test 25 as an Additional Wafer Sort Site and Copper Palladium Wires for Select 64Kb/16Kb/4Kb F-RAM Serial Industrial-grade Products.

To: GENERAL INBOX
PREMIER FARNELL
ProductChangeNotices@premierfarnell.com

Change Type: Major

Description of Change:

Cypress announces the qualification of Texas Instruments DMOS6 as an additional wafer fab site and Test 25 as an additional wafer sort site for its 64Kb/16Kb/4Kb F-RAM Serial Industrial-grade Product Family. This qualification is part of the flexible manufacturing initiative which allows Cypress to meet its delivery commitments in dynamic, changing market conditions.

Cypress also announces the qualification of Copper Palladium (CuPd) wire bonds for select lead frame products in the 64Kb/16Kb/4Kb F-RAM Serial Industrial-grade product family at United Test and Assembly Center Co., Ltd (UTAC) in Thailand using the Bill of Materials in the table below:

Material	Au Wire	CuPd Wire
Mold Compound	Sumitomo G600	Sumitomo G600
Lead Finish	Pure Sn	Pure Sn
Die Attach Epoxy	Henkel 8200T	Henkel 8600
Wire Diameter	0.9 mil	0.8 mil
Bond Wire	Au	CuPd

Benefit of Change:

By adding the DMOS6 and Test 25 sites, Cypress will have the added capability to meet upside market demand, and ensure consistent and reliable delivery to customers. The conversion to Copper Palladium wire bonds will keep Cypress aligned with the overall industry trend towards Copper based wire bonds.

Affected Parts: 60

Part Numbers Affected: See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

The changes listed in this PCN have been qualified through a series of tests documented in the Qualification Test Plan (QTP) reports indicated in the table below. These qualification reports can be found as attachments to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Qualification	QTP Report Number
TI DMOS6 Wafer Fab for 64Kb F-RAM Serial Industrial-Grade	154404
FRAM Wafer Sort at Test 25 Site	170503
64Kb F-RAM 8-Lead SOIC CuPd Wire at UTAC, Thailand	160608

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated sample ordering part numbers. Sample requests for products without samples built ahead of time will be built to order and subject to standard lead times. Please contact your Sales Representative as soon as possible to place any sample orders.

Qualification sample orders received after 30 days from the date of this PCN and qualification sample orders for parts which do not have a listed sample ordering part number in the table above will be subject to lead times.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file may be supplied from any of the qualified manufacturing sites.

Anticipated Impact:

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration